Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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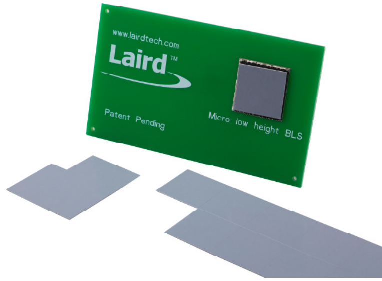
Tflex UT20000 Series

Ultra-Thin Thermal Gap Filler



Product Description

Tflex™ UT20000 is a specially formulated ultra-thin gap filler thermal interface material designed for thin interfaces that offers excellent thermal performance and high compliancy. It is designed without embedded reinforcing fiberglass to minimize contact resistance, yet still allows easy material handling and durability during assembly.

Tflex™ UT20000 provides excellent interfacing and its ability to wet out mating surfaces allows for efficient transfer of heat away from components. It is an ideal choice for low-pressure applications and optimum solution in handheld devices with thin interface gap and limited space requirements.

Tflex™ UT20000 is electrically non-conductive, stable from -50°C thru 200°C and offered in thicknesses that range from 0.008" (200 µm) up to 0.040" (1000 µm).

FEATURES AND BENEFITS

- Thermal Conductivity of 3.0 W/mK
- No fiberglass carrier to minimize thermal resistance, yet still easy to handle
- Excellent surface wetting for low contact resistance
- Unique formulation minimizes thermal resistance at low mounting forces
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	200 µm (0.008")- 1000 µm (0.040")	N/A
Thermal Conductivity (W/mK)	3.0	Hot Disk
Density (g/cc)	3.2	Helium Pyncometer
Hardness (Shore 00)	83.3 (200-375) µm 56.4 (400-1000) µm	ASTM D2240
Outgassing TML (weight %)	0.34%	ASTM E595
Outgassing CVCM (weight %)	0.09%	ASTM E595
Temperature Range	-50°C to 200°C	Laird Test Method
Rth@ 200 µm, 10 psi, 50^0 C	0.25°C–in2/W	ASTM D5470
Dielectric Constant @ 1MHz	5.87	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	2.2 x $10^{\wedge 15}$ ohm-cm	ASTM D257

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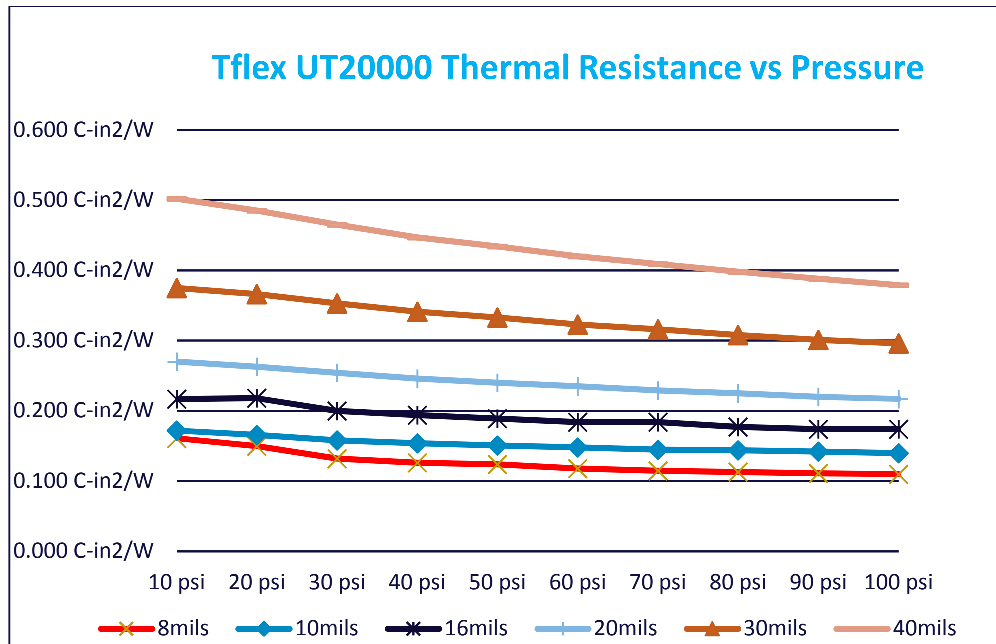


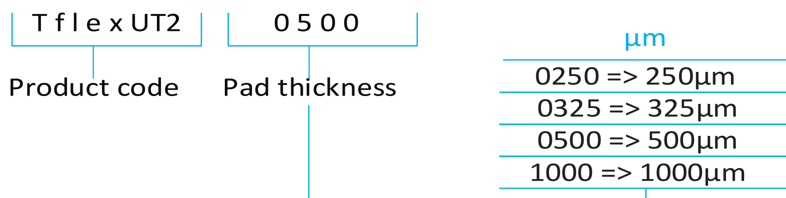
AVAILABILITY

STANDARD THICKNESSES

- 0.008" (200 µm) up to 0.040" (1000 µm) thick material available in 25 µm increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts. Custom die cut parts on a roll available for 200 µm (0.008") thru 375 µm (0.015")

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. UT20000 indicates Tflex UT20000 product line with thickness in microns



EXAMPLES:

- Tflex™ UT20200= 200 µm (0.008") thick Tflex™ UT20000 material
- Tflex™ UT20500= 500 µm (0.020") thick Tflex™ UT20000 material

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